ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES®

IPC-HDBK-610

Handbook and Guide to IPC-A-610 (Includes IPC-A-610B to C Comparison)

Developed by the IPC-HDBK-610 Task Group (7-31g) of the Product Assurance Committee (7-30) of IPC

Users of this standard are encouraged to participate in the development of future revisions.

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TABLE OF CONTENTS
Sorted in IPC-A-610 Revision C Order

IPC-A-610C	Page	IPC-A-610B	Page	HDBK-610	Page	Topic
3.2.1	3-4	1.1.1	3	3.2.1	13	Warning Labels
3.2.2	3-5	1.1.2	4	3.2.2	13	Protective Materials
3.3	**3-6**	**1.2**	**4**	**3.3**	**14**	**EOS/ESD Safe Workstation/EPA**
3.4	**3-8**	**1.3**	**5**	**3.4**	**16**	**Handling**
3.4.1	3-8	1.3	5	3.4.1	16	Guidelines
3.4.2	3-9	1.3	5	3.4.2	16	Physical Damage
3.4.3	3-9	1.3	5	3.4.3	16	Contamination
3.4.4	3-9	1.3	6	3.4.4	16	Electronic Assemblies
3.4.5	3-10	1.3	6	3.4.5	16	After Soldering
3.4.6	3-11	1.3	6	3.4.6	16	Gloves and Finger Cots
4	**4-1**	**2.0**	**7**	**4**	**17**	**Mechanical Assembly**
4.1	**4-2**	**2.1**	**8**	**4.1**	**17**	**Hardware**
4.2	**4-3**	**2.2**	**8**	**4.2**	**17**	**Hardware Mounting**
4.2.1	4-3	2.2.1	8	4.2.1	17	Electrical Clearance
4.2.2	4-4	4.2	55	4.2.2	17	Excess Solder
4.2.3	4-5	2.2.2	9	4.2.3	17	Threaded Fasteners
4.2.3.1	4-8			4.2.3.1	18	Minimum Torque for Electrical Connections
4.2.3.2	4-9			4.2.3.2	18	Wires
4.2.3.3	4-11			4.2.3.3	18	High Voltage Applications
4.2.4	4-12	2.2.3	10	4.2.4	18	Component Installation
4.2.4.1	4-12	2.2.3.1	10	4.2.4.1	18	High Power
4.2.4.2	4-14	2.2.3.2	11	4.2.4.2	18	Hole Obstruction for Solder Fill
4.3	**4-15**	**2.3**	**11**	**4.3**	**19**	**Swaged Hardware**
4.3.1	4-16	2.3.1	12	4.3.1	19	Flared Flange
4.3.1.1	4-17	2.3.1.1	13	4.3.1.1	19	Controlled Split
4.3.2	4-19	2.3.2	14	4.3.2	19	Flat Flange - Fused-in-Place
4.3.3	4-21	2.3.3	15	4.3.3	19	Terminals
4.4	**4-22**	**2.4**	**15**	**4.4**	**19**	**Component Mounting**
4.4.1	4-23	2.4.1	16	4.4.1	19	Mounting Clips
4.4.2	4-25	2.4.2	17	4.4.2	20	Adhesive Bonding - Non-Elevated Components
4.4.3	4-27	2.4.3	18	4.4.3	20	Adhesive Bonding - Elevated Components
4.4.4	4-28	2.4.4	20	4.4.4	20	Wire Hold Down
4.4.5	4-29	2.4.5	20	4.4.5	20	Cable Ties, Tie Wraps, Spot Ties
4.4.6	4-32	2.4.6	21	4.4.6	20	Lacing
4.4.7	4-33			4.4.7	20	Wire Dress for Terminations to Connectors Without Strain/Stress Relief
4.5	**4-34**	**2.5**	**22**	**4.5**	**20**	**Connectors, Handles, Extractors**
4.6	**4-35**	**2.6**	**22**	**4.6**	**21**	**Heat Sink**
4.6.1	4-37	2.6.1	23	4.6.1	21	Insulators and Thermal Compounds
4.6.2	4-38	2.6.2	24	4.6.2	21	Contact
4.7	**4-39**	**2.7**	**24**	**4.7**	**21**	**Terminals - Edge Clip**
4.8	**4-40**	**2.8**	**25**	**4.8**	**21**	**Connector Pins**
4.8.1	4-41	2.8.1	25	4.8.1	21	Edge Connector Pins
4.8.2	4-42	2.8.2	26	4.8.2	21	Press-Fit Pins
5	**5-1**	**3**	**29**	**5**	**22**	**Component Installation Location/ Orientation**
5.1	**5-2**	**3.1**	**30**	**5.1**	**22**	**Orientation**
5.1.1	5-2	3.1.1	30	5.1.1	22	Horizontal
5.1.2	5-4	3.1.2	31	5.1.2	22	Vertical

IPC-A-610C	Page	IPC-A-610B	Page	HDBK-610	Page	Topic
5.2	**5-5**	**3.2**	**31**	**5.2**	**22**	**Mounting**
5.2.1	5-5	3.2.1	31	5.2.1	22	Horizontal - Axial Leaded - Supported Holes
5.2.2	5-7			5.2.2	22	Horizontal - Axial Leaded - Unsupported Holes
5.2.3	5-8	3.2.2	32	5.2.3	22	Horizontal - Radial Leaded
5.2.4	5-9	3.2.3	32	5.2.4	23	Vertical - Axial Leaded - Supported Holes
5.2.5	5-11			5.2.5	23	Vertical - Axial Leaded Unsupported Holes
5.2.6	5-12	3.2.4	33	5.2.6	24	Vertical - Radial Leaded
5.2.6.1	5-13	2.4.3.1	19	5.2.6.1	24	Component Mounting Spacers
5.2.6.2	5-15	3.2.4	34	5.2.6.2	24	Component Meniscus
5.2.7	5-16	3.5.3	47	5.2.7	25	Wire/Lead Termination - Printed Board
5.2.7.1	5-16	3.5.3.1	47	5.2.7.1	25	Protrusion - Straight and Partially Clinched Leads
5.2.7.2	5-17	3.5.3.2	48	5.2.7.2	25	Clinched
5.2.8	5-19	3.2.5	34	5.2.8	26	Dual-In-line Pack (DIP)/Single-In-line Pack (SIP) Pins and Sockets
5.2.9	5-21	3.2.6	35	5.2.9	26	Connectors
5.2.10	5-23	3.2.7	36	5.2.10	26	Leads Crossing Conductors
5.3	**5-24**	**3.3**	**38**	**5.3**	**26**	**Lead Forming**
5.3.1	5-24	3.3	38	5.3.1	26	Bends
5.3.2	5-26	3.2.8	36	5.3.2	27	Stress Relief
5.3.2.1	5-26			5.3.2.1	27	Supported Holes
5.3.2.2	5-28			5.3.2.2	27	Unsupported Holes
5.3.2.3	5-29	3.2.8.1	37	5.3.2.3	27	Terminals
5.4	**5-30**	**3.4**	**38**	**5.4**	**27**	**Damage**
5.4.1	5-30	3.4.1	38	5.4.1	27	Lead
5.4.2	5-32	3.4.2	39	5.4.2	28	DIP and SOIC
5.4.3	5-33	3.4.3	39	5.4.3	28	Axial Lead and Glass Body/Seal
5.4.4	5-35	3.4.4	40	5.4.4	28	Radial (Two Lead)
5.5	**5-36**	**3.5.1**	**40**	**5.5**	**28**	**Terminals**
5.5.1	5-36	3.5.1.1	40	5.5.1	28	Wrap
5.5.1.1	5-37			5.5.1.1	28	Turrets and Straight Pins
5.5.1.2	5-38			5.5.1.2	28	Bifurcated Terminals
5.5.1.3	5-41			5.5.1.3	29	Pierced/Perforated Terminals
5.5.1.4	5-42			5.5.1.4	29	Hook Terminals
5.5.1.5	5-44			5.5.1.5	29	Series Connected Terminals
5.5.1.6	5-45			5.5.1.6	29	AWG 30 and Smaller Diameter Wires
5.5.1.7	5-46			5.5.1.7	29	Staked Wires/Components
5.5.2	5-47			5.5.2	29	Solder Cups
5.5.3	5-48	3.5.1.3	43	5.5.3	29	Stress Relief Lead/Wire Bend
5.5.4	5-50			5.5.4	30	Service Loops
5.5.5	5-51	3.5.1.4	44	5.5.5	30	Lead/Wire Placement
5.6	**5-52**	**3.5.2**	**45**	**5.6**	**30**	**Insulation**
5.6.1	5-52	3.5.2.1	45	5.6.1	30	Clearance
5.6.2	5-53	3.5.2.2	46	5.6.2	30	Damage
5.6.3	5-54	3.5.4	49	5.6.3	31	Flexible Sleeve
5.7	**5-55**	**3.5.2.3**		**5.7**	**31**	**Conductor**
5.7.1	5-55	3.5.2.3	46	5.7.1	31	Deformation
5.7.2	5-57	3.5.2.3	47	5.7.2	31	Damage
6	**6-1**	**4**	**51**	**6**	**32**	**Soldering**

IPC-A-610C	Page	IPC-A-610B	Page	HDBK-610	Page	Topic
6.1	**6-2**	**4.1**	**52**	**6.1**	**32**	**Soldering Acceptability Requirements**
		4.1	52	6.1.0.1	32	Wetting
				6.1.0.2	32	Wetting and Solderability
				6.1.0.3	33	Solder Connections to Gold Plated Leads
6.2	**6-4**			**6.2**	**33**	**Lead Protrusion**
6.3	**6-5**	**4.2**	**54**	**6.3**	**33**	**Plated-Through Holes (PTH) (Supported Holes)**
6.3.1	6-6	4.1	52	6.3.1	33	Vertical Fill of Hole
6.3.2	6-8	4.1	52	6.3.2	34	Circumferential Wetting - Primary Side
6.3.2.1	6-8	4.1	52	6.3.2.1	34	Lead and Barrel
6.3.2.2	6-9	4.1	52	6.3.2.2	34	Land Area Coverage - Primary Side
6.3.3	6-10	4.1	52	6.3.3	34	Circumferential Wetting - Secondary Side (PTH and Unsupported Holes)
6.3.4	6-11	4.2	54	6.3.4	34	PTH Mounted Components
6.3.4.1	6-11			6.3.4.1	34	Solder Conditions
6.3.4.2	6-13			6.3.4.2	34	Solder in Lead Bend
6.3.4.3	6-14	4.2	57	6.3.4.3	34	Meniscus in Solder
6.3.5	6-15			6.3.5	35	Coated Wire Insulation in Solder
6.3.6	6-16	4.2.4	57	6.3.6	35	Interfacial Connection without Lead - Vias
6.4	**6-17**			**6.4**	**35**	**Unsupported Holes**
6.5	**6-20**			**6.5**	**35**	**Other**
6.5.1	6-20	4.2.2	56	6.5.1	35	Lead Cutting After Soldering
6.5.2	6-21	4.2.1	56	6.5.2	35	Exposed Basis Material
6.5.3	6-23	4.1	52	6.5.3	36	Excess Solder
6.5.3.1	6-23	4.1	53	6.5.3.1	36	Solder Balls/Splashes
6.5.3.2	6-24	4.1	52	6.5.3.2	36	Solder Bridging
6.5.3.3	6-25	4.1	53	6.5.3.3	36	Solder Webbing
6.5.4	6-26	4.1	52	6.5.4	36	Pin Holes/Blow Holes
6.5.5	6-27	4.2	55	6.5.5	36	Soldering Projections
6.5.6	6-28			6.5.6	36	Nonwetting
6.6	**6-29**	**4.3**	**58**	**6.6**	**37**	**Terminals**
6.6.1	6-30			6.6.1	37	Bifurcated
6.6.2	6-31			6.6.2	37	Turret
6.6.3	6-32			6.6.3	37	Hook/Pin
6.6.4	6-33			6.6.4	37	Pierced Tab
6.6.5	6-34			6.6.5	37	Solder Cups
6.6.6	6-35			6.6.6	38	Flared Flange Hardware
6.7	**6-37**	**4.3.1**	**58**	**6.7**	**38**	**Insulation**
6.7.1	6-37	4.1	53	6.7.1	38	In Solder
6.7.2	6-38	4.1	53	6.7.2	38	Damage
6.7.3	6-39			6.7.3	38	Clearance
6.8	**6-40**			**6.8**	**38**	**High Voltage**
6.8.1	6-40			6.8.1	39	Terminals
6.8.1.1	6-40			6.8.1.1	39	Wires/Leads
6.8.1.2	6-42			6.8.1.2	39	Bottom Terminations
6.8.1.3	6-43			6.8.1.3	39	Unused
6.8.2	6-44			6.8.2	39	Solder Cups
6.8.2.1	6-44			6.8.2.1	39	Wires/Leads
6.8.2.2	6-45			6.8.2.2	39	Unused

IPC-A-610C	Page	IPC-A-610B	Page	HDBK-610	Page	Topic
6.8.3	6-46			6.8.3	39	Insulation
6.8.4	6-47			6.8.4	39	Through-Hole Connections
6.8.5	6-48			6.8.5	39	Flared Flange Terminals
6.9	**6-49**	**4.5**	**60**	**6.9**	**39**	**Connector Pins - Press-Fit Pins**
6.10	**6-51**	**4.4**	**60**	**6.10**	**39**	**Gold Fingers**
7	**7-1**	**5**	**63**	**7**	**40**	**Cleanliness**
7.1	**7-2**	**5.1**	**64**	**7.1**	**40**	**Flux Residues**
7.2	**7-3**	**5.2**	**65**	**7.2**	**40**	**Particulate Matter**
7.3	**7-4**	**5.3**	**65**	**7.3**	**40**	**Chlorides, Carbonates, and White Residues**
7.4	**7-6**			**7.4**	**41**	**Flux Residues - No Clean Process Appearance**
7.5	**7-7**	**5.4**	**66**	**7.5**	**41**	**Surface Appearance**
8	**8-1**	**6**	**67**	**8**	**42**	**Marking**
8.1	**8-2**	**6.1**	**68**	**8.1**	**42**	**Etched Marking (including Hand Printing)**
8.2	**8-3**	**6.2**	**69**	**8.2**	**42**	**Screened Marking**
8.3	**8-3**	**6.3**	**70**	**8.3**	**42**	**Stamped Marking**
8.4	**8-6**	**6.4**	**71**	**8.4**	**42**	**Laser Marking**
8.5	**8-8**	**6.5**	**72**	**8.5**	**42**	**Labels**
8.5.1	8-8	6.5	72	8.5.1	42	Bar Coding
8.5.2	8-8	6.5.1	72	8.5.2	42	Readability
8.5.3	8-9	6.5.2	72	8.5.3	42	Adhesion and Damage
9	**9-1**	**7**	**73**	**9**	**43**	**Coatings**
9.1	**9-2**	**7.1**	**74**	**9.1**	**43**	**Conformal Coating**
9.1.1	9-2	7.1.1	74	9.1.1	43	General
9.1.2	9-3	7.1.2	74	9.1.2	43	Coverage
9.1.3	9-6	7.1.3	75	9.1.3	43	Thickness
9.2	**9-7**	**7.2**	**76**	**9.2**	**43**	**Solder Resist Coating**
9.2.1	9-8	7.2.1	76	9.2.1	43	Wrinkling/Cracking
9.2.2	9-10	7.2.2	77	9.2.2	43	Voids and Blisters
9.2.3	9-12	7.2.3	77	9.2.3	43	Breakdown
10	**10-1**	**8**	**79**	**10**	**44**	**Laminate Conditions**
10.1	**10-1**	**8.1**	**80**	**10.1**	**44**	**Introduction**
10.1.1	10-2			10.1.1	44	Identification of Defects
10.2	**10-3**			**10.2**	**44**	**Laminate Damage**
10.2.1	10-3	8.2.1	81	10.2.1	44	Measling and Crazing
10.2.2	10-5	8.2.3	82	10.2.2	45	Blistering and Delamination
10.2.3	10-8	8.2.4	83	10.2.3	45	Weave Texture/Weave Exposure
10.2.4	10-9	8.2.6	84	10.2.4	45	Haloing and Edge Delamination
10.2.5	10-11	8.2.7	85	10.2.5	46	Pink Ring
10.3	**10-12**			**10.3**	**46**	**Flexible and Rigid-Flex Printed Wiring**
10.4	**10-14**			**10.4**	**47**	**Solder Resist Discoloration**
10.5	**10-15**	**8.2.8**	**85**	**10.5**	**47**	**Burns**
10.6	**10-16**	**8.3**	**86**	**10.6**	**47**	**Bow and Twist**
10.7	**10-17**			**10.7**	**47**	**Conductor/Land Damage**
10.7.1	10-17			10.7.1	47	Reduction in Cross-Sectional Area
10.7.2	10-18			10.7.2	48	Lifted Pads/Lands
11	**11-1**	**9**	**87**	**11**	**49**	**Discrete Wiring**
11.1	**11-2**	**9.1**	**88**	**11.1**	**49**	**Solderless Wrap**
11.1.1	11-3	9.1.1	88	11.1.1	49	Number of Turns

IPC-A-610C	Page	IPC-A-610B	Page	HDBK-610	Page	Topic
11.1.2	11-14	9.1.2	89	11.1.2	50	Turn Spacing
11.1.3	11-5	9.1.3	90	11.1.3	50	End Tails, Insulation Wrap
11.1.4	11-7	9.1.4	91	11.1.4	50	Raised Turns Overlap
11.1.5	11-8	9.1.5	92	11.1.5	50	Connection Position
11.1.6	11-10	9.1.6	93	11.1.6	50	Wire Dress
11.1.7	11-11	9.1.7	93	11.1.7	50	Wire Slack
11.1.8	11-12	9.1.8	94	11.1.8	50	Plating
11.1.9	11-13	9.1.9	94	11.1.9	50	Damaged Insulation & Terminals
11.1.10	11-14	9.1.9	95	11.1.10	50	Conductor Damage
11.2	**11-15**	**9.3**	**98**	**11.2**	**50**	**Jumper Wires**
11.2.1	11-16	9.3.1	99	11.2.1	50	Wire Selection
11.2.2	11-17	9.3.2	99	11.2.2	50	Wire Routing
11.2.2.1	11-18			11.2.2.1	50	Component Side
11.2.2.2	11-19			11.2.2.2	50	PTH Termination Side
11.2.3	11-20	9.3.3	101	11.2.3	50	Wire Staking
11.2.4	11-22	9.3.4	102	11.2.4	51	Plated-Through Holes
11.2.4.1	11-23			11.2.4.1	51	Lead in Hole
11.2.4.2	11-24			11.2.4.2	51	Wrapped Attachment
11.2.4.3	11-25			11.2.4.3	51	Lap Soldered
11.2.5	11-26	9.3.5	103	11.2.5	51	SMT
11.2.5.1	11-26			11.2.5.1	51	Chip and Cylindrical End Cap Components
11.2.5.2	11-27			11.2.5.2	51	Gull Wing
11.2.5.3	11-28			11.2.5.3	51	J-Lead
11.2.5.4	11-28			11.2.5.4	51	Vacant Land/Pad
12	**12-1**	**10**	**105**	**12**	**52**	**Surface Mount Assemblies**
				12.0.1	52	Guidelines for Placement of SMT Components
				12.0.1.1	52	Small Devices Incorporating Two Terminations
				12.0.1.2	52	Mounting of Cylindrical End Cap (MELF) Devices
				12.0.1.3	52	Registration of Castellated Chip Carriers
				12.0.1.4	52	Surface Mounted Device Lead and Land Contact
				12.0.1.5	52	Surface Mounted Device Lead Side Overhang
				12.0.1.6	52	Surface Mounted Device Lead Toe Overhang
				12.0.1.7	52	Surface Mounted Device Lead Heel Clearance
				12.0.1.8	52	Surface Mounted Device Lead Height Off Land (Prior to Soldering)
				12.0.1.9	53	Positioning of ''J'' Leaded Devices
				12.0.1.10	53	Positioning Gull-Wing Leaded Devices
				12.0.1.11	53	Other Devices
12.1	**12-3**	**10.1**	**106**	**12.1**	**53**	**Staking Adhesive**
12.2	**12-5**	**10.2**	**107**	**12.2**	**53**	**Solder Joints**
12.2.1	12-5	10.2.1	107	12.2.1	53	Chip Components - Bottom Only Terminations
12.2.1.1	12-6			12.2.1.1	53	Side Overhang (A)
12.2.1.2	12-7			12.2.1.2	53	End Overhang (B)
12.2.1.3	12-8			12.2.1.3	53	End Joint Width (C)
12.2.1.4	12-9			12.2.1.4	53	Side Joint Length (D)
12.2.1.5	12-10			12.2.1.5	53	Maximum Fillet Height (E)
12.2.1.6	12-1			12.2.1.6	53	Minimum Fillet Height (F)

IPC-A-610C	Page	IPC-A-610B	Page	HDBK-610	Page	Topic
12.2.1.7	12-11			12.2.1.7	54	Solder Thickness (G)
12.2.2	12-12	10.2.2	109	12.2.2	54	Chip Components - Rectangular or Square End Components - 1, 3, or 5 Side Termination
12.2.2.1	12-13			12.2.2.1	54	Side Overhang (A)
12.2.2.2	12-15			12.2.2.2	54	End Overhang (B)
12.2.2.3	12-16			12.2.2.3	54	End Joint Width (C)
12.2.2.4	12-18			12.2.2.4	54	Side Joint Length (D)
12.2.2.5	12-19			12.2.2.5	54	Maximum Fillet Height (E)
12.2.2.6	12-20			12.2.2.6	54	Minimum Fillet Height (F)
12.2.2.7	12-21			12.2.2.7	54	Solder Thickness (G)
12.2.2.8	12-22			12.2.2.8	54	End Overlap (J)
12.2.3	12-23	10.2.3	112	12.2.3	55	Cylindrical End Cap Termination
12.2.3.1	12-24			12.2.3.1	55	Side Overhang (A)
12.2.3.2	12-25			12.2.3.2	55	End Overhang (B)
12.2.3.3	12-26			12.2.3.3	55	End Joint Width (C)
12.2.3.4	12-27			12.2.3.4	55	Side Joint Length (D)
12.2.3.5	12-28			12.2.3.5	55	Maximum Fillet Height (E)
12.2.3.6	12-29			12.2.3.6	55	Minimum Fillet Height (F)
12.2.3.7	12-30			12.2.3.7	55	Solder Thickness (G)
12.2.3.8	12-31			12.2.3.8	55	End Overlap (J)
12.2.4	12-32	10.2.4	115	12.2.4	56	Leadless Chip Carriers with Castellated Terminations
12.2.4.1	12-33			12.2.4.1	56	Side Overhang (A)
12.2.4.2	12-34			12.2.4.2	56	End Overhang (B)
12.2.4.3	12-35			12.2.4.3	56	Minimum End Joint Width (C)
12.2.4.4	12-36			12.2.4.4	56	Minimum Side Joint Length (D)
12.2.4.5	12-37			12.2.4.5	56	Maximum Fillet Height (E)
12.2.4.6	12-37			12.2.4.6	56	Minimum Fillet Height (F)
12.2.4.7	12-38			12.2.4.7	56	Solder Thickness (G)
12.2.5	12-39	10.2.5	118	12.2.5	56	Flat Ribbon L and Gull Wing Leads
12.2.5.1	12-39			12.2.5.1	56	Side Overhang (A)
12.2.5.2	12-43			12.2.5.2	56	Toe Overhang (B)
12.2.5.3	12-44			12.2.5.3	56	Minimum End Joint Width (C)
12.2.5.4	12-46			12.2.5.4	57	Minimum Side Joint Length (D)
12.2.5.5	12-47			12.2.5.5	57	Maximum Heel Fillet Height (E)
12.2.5.6	12-48			12.2.5.6	57	Minimum Fillet Height (F)
12.2.5.7	12-50			12.2.5.7	57	Solder Thickness (G)
12.2.6	12-51	10.2.6	121	12.2.6	57	Round or Flattened (Coined Leads)
12.2.6.1	12-51			12.2.6.1	58	Side Overhang (A)
12.2.6.2	12-52			12.2.6.2	52	Toe Overhang (B)
12.2.6.3	12-52			12.2.6.3	52	Minimum End Joint Width (C)
12.2.6.4	12-53			12.2.6.4	52	Minimum Side Joint Width (D)
12.2.6.5	12-54			12.2.6.5	52	Maximum Heel Fillet Height (E)
12.2.6.6	12-55			12.2.6.6	52	Minimum Heel Fillet Height (F)
12.2.6.7	12-56			12.2.6.7	52	Solder Thickness (G)
12.2.6.8	12-56			12.2.6.8	52	Minimum Side Joint Height (Q)
12.2.7	12-57	10.2.7	124	12.2.7	52	J-Leads
12.2.7.1	12-57			12.2.7.1	52	Side Overhang (A)
12.2.7.2	12-59			12.2.7.2	58	Toe Overhang (B)

IPC-A-610C	Page	IPC-A-610B	Page	HDBK-610	Page	Topic
12.2.7.3	12-60			12.2.7.3	58	End Joint Width (C)
12.2.7.4	12-61			12.2.7.4	58	Side Joint Length (D)
12.2.7.5	12-62			12.2.7.5	59	Maximum Fillet Height (E)
12.2.7.6	12-63			12.2.7.6	59	Minimum Heel Fillet Height (F)
12.2.7.7	12-65			12.2.7.7	59	Minimum Solder Thickness (G)
12.2.8	12-66	10.2.8	127	12.2.8	59	Butt/I Joints
12.2.8.1	12-66			12.2.8.1	59	Maximum Side Overhang (A)
12.2.8.2	12-67			12.2.8.2	59	Maximum Toe Overhang (B)
12.2.8.3	12-67			12.2.8.3	59	Minimum End Joint Width (C)
12.2.8.4	12-68			12.2.8.4	59	Minimum Side Joint Length (D)
12.2.8.5	12-68			12.2.8.5	59	Maximum Fillet Height (E)
12.2.8.6	12-69			12.2.8.6	59	Minimum Fillet Height (F)
12.2.8.7	12-69			12.2.8.7	59	Solder Thickness (G)
12.2.9	12-70			12.2.9	59	Flat Lug Leads
12.2.10	12-71			12.2.10	59	Tall Profile Components Having Bottom Only Terminations
12.2.11	12-72			12.2.11	59	Inward Formed L-Shaped Ribbon Leads
12.2.12	12-74			12.2.12	59	Area Array/Ball Grid Array
12.3	**12-77**	**10.3**	**129**	**12.3**	**60**	**Chip Component - Termination Variations**
				12.3.0.1	60	Chip Components - Termination Variations - Three or Five Side Terminations - Stacking
12.3.1	12-77			12.3.1	60	Chip Components - Termination Variations Three or Five Side Terminations - Mounting on Side
12.3.2	12-78			12.3.2	60	Deposited Electrical Elements - Mounting Upside Down
12.4	**12-79**	**10.3**	**129**	**12.4**	**60**	**SMT Soldering Anomalies**
12.4.1	12-79			12.4.1	60	Tombstoning
12.4.2	12-80			12.4.2	60	Coplanarity
12.4.3	12-81			12.4.3	60	Reflow of Solder Paste
12.4.4	12-82			12.4.4	60	Nonwetting
12.4.5	12-83			12.4.5	61	Dewetting
12.4.6	12-84			12.4.6	61	Disturbed Solder
12.4.7	12-85			12.4.7	61	Fractured Solder
12.4.8	12-86			12.4.8	61	Pinholes/Blowholes
12.4.9	12-87			12.4.9	61	Bridging
12.4.10	12-88		129	12.4.10	61	Solder Balls/Solder Fines
12.4.11	12-89		129	12.4.11	62	Solder Webbing
12.5	12-90	10.4	130	12.5	62	Component Damage
12.5.1	12-90	10.4.1.1	131	12.5.1	62	Cracks and Chip-Outs
12.5.2	12-93	10.4.1.2		12.5.2	62	Metallization
12.5.3	12-94	10.4.2.1		12.5.3	62	Leaching
Appendix A					**63**	**Electrical Conductor Spacing Appendix A**
				Appendix B	**65**	**Metric Conversion Information, Appendix H-1**
				Appendix C	**70**	**Comparison of IPC-A-610 Revision B to C**
				Appendix D	**84**	**U.S. Department of Defense Adoption Notice**
				Misc.	**1**	**IPC-A-610C Amendment 1**

Handbook and Guide to IPC-A-610 (Includes IPC-A-610B to C Comparison)

1 ACCEPTABILITY OF ELECTRONIC ASSEMBLIES

1.0.1 Preamble/Foreword This handbook is a companion reference to and was prepared using IPC-A-610C and IPC-A-610C Amendment 1. The amendment provides additional criteria and clarification statements. The amendment is included with this handbook following Appendix C and can be downloaded at no cost from the IPC website at the following link:

www.ipc.org/html/610C%2BAmendment.pdf

Electrical Conductor Spacing that is provided in IPC-A-610C Appendix A has been incorporated into the text of this handbook and is also included as Appendix A to this handbook.

Information on metric conversion is provided as Appendix B.

An expanded subject matter based cross-reference of the two versions is provided in Appendix C.

A copy of the IPC-A-610 Department of Defense Adoption Notice is provided as Appendix D.

The intent of this handbook is to explain the technical rationale for selected Acceptability, Process Indicator and Defect criteria and to provide information regarding assembly technology. Additional information is provided to give a broader understanding of the process considerations needed for the production of acceptable hardware.

Note: Not all information provided in IPC-A-610C is addressed in this handbook.

While IPC-T-50 establishes unique definitions for the acronyms PCB, PWB, PCA and PWA, the term PCB (printed circuit board) is used generically in this handbook.

1.0.2 Format of this Handbook The section and paragraph numbers in this handbook refer and correspond to the section and paragraph numbers in Revision C of IPC-A-610. Where used verbatim, text of IPC-A-610C is identified by being boxed.

For the purposes of the handbook, a capitalized ''Standard'' in the handbook text refers to IPC-A-610C. It should also be noted that any references in the handbook text (not text taken from the Standard) refer to sections, tables, and figures in the handbook; see Example 1. References in the handbook text to sections, tables, and figures in the Standard will be followed by ''of the Standard''; see Example 2.

Example 1:

4.4.2 For more information on adhesive on areas to be soldered see 12.1 on page 12-3 of the Standard.

Example 2:

9.1.2 For more information on magnification power for inspection see Table 1-2 of the Standard.

Text excerpted from documents other than IPC-A-610 is shown in **BOLD SMALL CAPS** to assist with clarity.

1.0.3 Supplemental Definitions These supplemental definitions are provided to assist the reader in understanding the intent of portions of the text of the Standard. Terms used in the Standard or this Handbook and not otherwise defined are defined as follows. Definitions from IPC-T-50 are identified with *.

Barely/slight – By a very little, almost not discernable/measurable/perceptible.

Clearly – Free from anything that dims, obscures or inhibits observation. Easily discernable to the eye.

Coefficient of Thermal Expansion – The CTE is the amount that a material (component, PWB laminate, etc.) changes dimension as a result of temperature change. The CTE is expressed in parts per million per degree Celsius (p/m/C°). The CTE differential that exists between the component and the PWB is a factor in determining the reliability of the assembly. If a ceramic surface mount component that has a CTE of 6p/m/C° is placed on a laminate material such as FR-4 that has a CTE of 14 - 16 p/m/C°, the designer needs to assure that compliance of the component leads is sufficient to accommodate the differential in CTE. The coefficient of thermal expansion (CTE) is sometimes also referred to as the Thermal Coefficient of Expansion (TCE). In this Handbook the term CTE is used.

Disposition – A final settlement. The act of identifying the action to be taken on a Defect.

Minimum Electrical Clearance (Minimum Electrical Spacing)* – The minimum allowable distance between adjacent conductors, at a given voltage and altitude, that is sufficient to prevent dielectric breakdown, corona, or both from occurring between the conductors. Minimum electrical clearance is a value determined by the designer and is based on multiple factors.

Pitch – The nominal center-to-center distance of adjacent conductors. When the conductors are of equal size and their spacing is uniform, the pitch is usually measured from

the reference edge of the adjacent conductors, as illustrated in Figure 1-1.

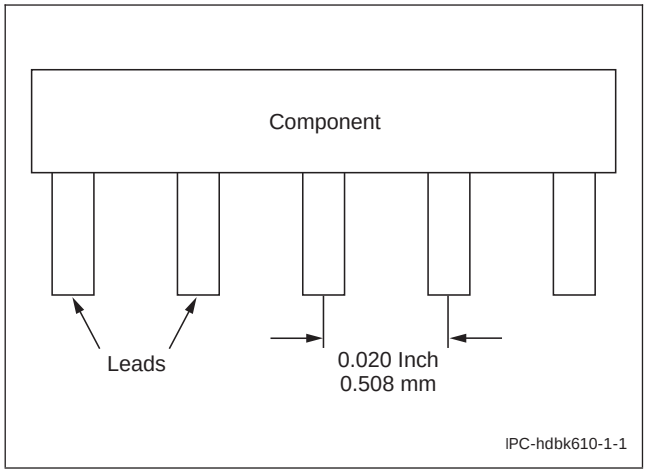

Figure 1-1 Pitch

When referring to a device as being a ''20 mil pitch component'' that means that the leads are 0.020 inch apart measured center-to-center.

***Repair** –** The act of restoring the functional capability of a defective article in a manner that precludes compliance of the article with applicable drawings or specifications.

***Rework** –** The act of reprocessing noncomplying articles, through the use of original or alternate equivalent processing, in a manner that assures compliance of the article with applicable drawings or specifications.

***Scrap* –** In some cases the cost to repair an assembly exceeds the cost to replace it with a like item or may cause the assembly to be unreliable. In such cases the defective assembly is usually dispositioned as Scrap.

***Use-As-Is* –** Products containing defects that do not impact performance may sometimes be dispositioned Use-As-Is. For instance, loss of date code part marking on a finished assembly is a Defect, but not a Defect that affects the performance of the product. Such a Defect could be dispositioned Use-As-Is. The disposition Use-As-Is may require approval of the customer/user.

1.0.4 Background on IPC-A-610 Revision C The Standard is an industry consensus document published by IPC. The technical content and criteria of any amendments or revisions to the IPC-A-610 were developed by the collective efforts of the IPC Task Group 7-31b under the 7-30 Product Assurance Committee. This Task Group is comprised of individuals from a wide sector of the electronics manufacturing community. IPC-A-610 is currently in its ''C'' Revision meaning it has been revised three times since its initial release.

1.1 Scope

1.1 Scope

This standard is a collection of visual quality acceptability requirements for electronic assemblies. It was prepared by the Product Assurance Committee of the IPC.

This document presents acceptance requirements for the manufacture of electrical and electronic assemblies. Historically, electronic assembly standards contained a more comprehensive tutorial addressing principles and techniques. For a more complete understanding of this document's recommendations and requirements, one may use this document in conjunction with IPC-HDBK-001 and J-STD-001.

IPC-A-610 has criteria outside the scope of J-STD-001 defining handling, mechanical and other workmanship requirements. Table 1-1 is a summary of related documents.

The Standard provides visual characteristics of products with criteria that can be applied without making physical measurements to the electronic assembly to determine final acceptability (unless for referee purposes); see 1.4.3 regarding the relationship between the IPC-A-610 and the J-STD-001.

1.2 Purpose

1.2 Purpose

The visual standards in this document reflect the requirements of existing IPC and other applicable specifications.

In order for the user to apply and use the content of this document, the assembly/product should comply with other existing IPC requirements, such as IPC-SM-782, IPC-2221, IPC-6011 and IPC-A-600. If the assembly does not comply with these or equivalent requirements, then the acceptance criteria needs to be defined between the customer and supplier.

The illustrations in this document portray specific points noted in the title of each page. A brief description follows each illustration. It is not the intent of this document to exclude any Acceptable procedure for component placement or for applying flux and solder used to make the electrical connection; however, the methods used must produce completed solder joints conforming to the acceptability requirements described in this document.

In the case of a discrepancy, the description or written criteria always takes precedence over the illustrations.

Existing IPC and applicable industry specifications have been selected to reflect Best Manufacturing Practices.

The intent is not to require the use of the Standards listed by Table 1-1, but rather to advise or warn users of IPC-A-610C that unless acceptable guidelines and requirements are used in the design of equipment, the acceptability criteria depicted by the Standard may not be achievable. For example, if a design standard other than IPC-2221 was used to design a SMT printed wiring board assembly, there

is no assurance that the ratio of component footprint to termination area defined by the alternative design criteria would result in an interface that would allow the heel fillet criteria of the Standard to be achieved. If alternative or unique design criteria are used then the User and the Supplier (Assembler) should agree on appropriate acceptance criteria.

IPC-A-610 defines the visual acceptance criteria for various attributes and does not address the processes or procedures required for the assembly of electronic equipment. Any process that produces hardware that complies with the acceptability criteria of IPC-A-610 is acceptable, unless other applicable requirements (contract, master drawing, approved assembly drawing, etc.) define or specify the process(es) to be used. Other standards, such as EIA/IPC J-STD-001, should be consulted for information on process control, frequency of inspection and type of inspection (100% or Sample Inspection).

The written criteria **always** take precedence over illustrations in the Standard. Both courts and industry experts have held that when observing a drawing, figure or photograph, each viewer sees something slightly different. Such differences may be caused by anomalies in color vision, subtle prejudices, etc. Therefore, acceptability decisions must be made based on the written criteria for each attribute.

1.3 Specialized Designs

1.3 Specialized Designs

IPC-A-610, as an industry consensus document, cannot address all of the possible components and product design combinations. However, the standard does provide criteria for commonly used technologies. Where uncommon or specialized components or technologies are necessary, good judgment should be used while applying the criteria of this standard. However, where similar characteristics exist, this document may provide guidance for product acceptance criteria. Often, unique definition is necessary to consider the specialized characteristics while considering product performance criteria. The development should include customer involvement or consent and the criteria should include agreed definition of product acceptance.

Whenever possible this criteria should be submitted to the IPC Technical Committee to be considered for inclusion in upcoming revisions of this standard.

It wasn't possible to include all possible design considerations in the Standard.

With the use of good judgement, acceptability criteria of the Standard may be adopted for uncommon technologies. The user should approve acceptability criteria developed for unique designs or assembly procedures.

1.4 Terms & Definitions

1.4 Terms & Definitions

Items noted with an * are quoted from IPC-T-50, ''Terms and Definitions for Interconnecting and Packaging Electronic Circuits.''

IPC documents, including the Standard and this Handbook, depend on IPC-T-50 for the definitions of common terms. Where special definitions need to be established, each document establishes those definitions individually. Definitions listed in 1.4 through 1.4.8 of the Standard are supplemental to the definitions provided by IPC-T-50. This Handbook provides additional definitions of terms used in the Standard.

1.4.1 Classification

1.4.1 Classification

Criteria defined in this document reflect three classes, which are as follows:

Class 1 - General Electronic Products
Includes consumer products, some computer and computer peripherals suitable for applications where cosmetic imperfections are not important and the major requirement is function of the completed electronic assembly.

Class 2 - Dedicated Service Electronic Products
Includes communications equipment, sophisticated business machines, and instruments where high performance and extended life is required and for which uninterrupted service is desired but not critical. Certain cosmetic imperfections are allowed.

Class 3 - High Performance Electronic Products
Includes the equipment and products where continued performance or performance-on-demand is critical. Equipment downtime cannot be tolerated and must function when required, such as in life support items or flight control systems. Assemblies in this class are suitable for applications where high levels of assurance are required, service is essential, or the end-use environment may be uncommonly harsh.

Product Class definitions are consistent throughout IPC Standards. The descriptions of product classes are intentionally general due to the wide variety of products that may be assembled using the requirements of the Standard.

Users and manufacturers need to agree on the Product Class; see 1.4.2. The Product Class should be determined based on the end-use environment and criticality of functional availability of the end product.